

Kui Xiao

List of Publications by Year in descending order

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citing authors

| # | ARTICLE | IF | CITATIONS |
|----|--|-----|-----------|
| 1 | Microstructure and Grain Boundary Corrosion Mechanism of Pearlitic Material. Journal of Materials Engineering and Performance, 2022, 31, 483-494. | 2.5 | 6 |
| 2 | Microbiologically Influenced Corrosion of AA 6061 with Bacillus Species in an Environment Containing an Organic Nitrogen Source. Journal of Materials Engineering and Performance, 2022, 31, 1870-1880. | 2.5 | 1 |
| 3 | Image Deep Learning Assisted Prediction of Mechanical and Corrosion Behavior for Al-Zn-Mg Alloys. IEEE Access, 2022, 10, 35620-35631. | 4.2 | 4 |
| 4 | Effect of Fungus, Aspergillus sp. F1-1, on the corrosion behavior of PCB-HASL in humid atmospheric environment. Surface Topography: Metrology and Properties, 2022, 10, 015022. | 1.6 | 1 |
| 5 | Effect of Concentrations of Fe ²⁺ and Fe ³⁺ on the Corrosion Behavior of Carbon Steel in Cl ⁻ and SO ₄ ²⁻ Aqueous Environments. Metals and Materials International, 2021, 27, 2623-2633. | 3.4 | 21 |
| 6 | Electrochemical migration behavior of moldy printed circuit boards in a 10 mT magnetic field. RSC Advances, 2021, 11, 28178-28188. | 3.6 | 0 |
| 7 | Unexpected Stress Corrosion Cracking Improvement Achieved by Recrystallized Layer in Al-Zn-Mg Alloy. Journal of Materials Engineering and Performance, 2021, 30, 6258-6268. | 2.5 | 5 |
| 8 | A novel extraction method of device parameters for thin-film transistors (TFTs). Physics Letters, Section A: General, Atomic and Solid State Physics, 2021, 403, 127386. | 2.1 | 5 |
| 9 | The Passivity of Pure Nickel in Alkaline Solution under Different Temperatures: Electrochemical Verification and First-Principles Calculation. Journal of Materials Engineering and Performance, 2021, 30, 1737-1747. | 2.5 | 2 |
| 10 | Effect of static magnetic field on mold corrosion of printed circuit boards. Bioelectrochemistry, 2020, 131, 107394. | 4.6 | 9 |
| 11 | Effect of Manufacturing Parameters on the Mechanical and Corrosion Behavior of Selective Laser Melted 15%PH Stainless Steel. Steel Research International, 2020, 91, 1900447. | 1.8 | 21 |
| 12 | Co-enhancing the Mechanical Property and Corrosion Resistance of Selective Laser Melted High-Strength Stainless Steel via Cryogenic Treatment. Journal of Materials Engineering and Performance, 2020, 29, 7052-7062. | 2.5 | 5 |
| 13 | Corrosion Acceleration of Printed Circuit Boards With an Immersion Silver Layer Exposed to Bacillus cereus in an Aerobic Medium. Frontiers in Microbiology, 2019, 10, 1493. | 3.5 | 10 |
| 14 | Comparative study on extraction methods of threshold voltage for thin-film transistors. Journal of the Society for Information Display, 2019, 27, 816-821. | 2.1 | 2 |
| 15 | Atmospheric corrosion behavior of low-alloy steels in a tropical marine environment. Journal of Iron and Steel Research International, 2019, 26, 1315-1328. | 2.8 | 23 |
| 16 | Electrochemical migration failure mechanism and dendrite composition characteristics of Sn _{96.5} Ag _{3.0} Cu _{0.5} alloy in thin electrolyte films. Journal of Materials Science: Materials in Electronics, 2019, 30, 6575-6582. | 2.2 | 13 |
| 17 | Influence of atmospheric particulates on initial corrosion behavior of printed circuit board in pollution environments. Applied Surface Science, 2019, 467-468, 889-901. | 6.1 | 8 |
| 18 | The influence of <i>Bacillus subtilis</i> on tin-coated copper in an aqueous environment. RSC Advances, 2018, 8, 4671-4679. | 3.6 | 5 |

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|----|---|------|-----------|
| 19 | Microporous corrosion behavior of gold-plated printed circuit boards in an atmospheric environment with high salinity. <i>Journal of Materials Science: Materials in Electronics</i> , 2018, 29, 8877-8885. | 2.2 | 6 |
| 20 | Effects of mould on electrochemical migration behaviour of immersion silver finished printed circuit board. <i>Bioelectrochemistry</i> , 2018, 119, 203-210. | 4.6 | 25 |
| 21 | Role of mold in electrochemical migration of copper-clad laminate and electroless nickel/immersion gold printed circuit boards. <i>Materials Letters</i> , 2018, 210, 283-286. | 2.6 | 9 |
| 22 | Atmospheric corrosion factors of printed circuit boards in a dry-heat desert environment: Salty dust and diurnal temperature difference. <i>Chemical Engineering Journal</i> , 2018, 336, 92-101. | 12.7 | 36 |
| 23 | Effect of iron ion diffusion on the corrosion behavior of carbon steels in soil environment. <i>RSC Advances</i> , 2018, 8, 40544-40553. | 3.6 | 15 |
| 24 | Surface failure mechanism of PCB-ENIG in typical outdoor atmospheric environments. <i>Materials Research Bulletin</i> , 2017, 91, 179-188. | 5.2 | 22 |
| 25 | Surface failure analysis of a field-exposed copper-clad plate in a marine environment with industrial pollution. <i>Applied Surface Science</i> , 2017, 399, 608-616. | 6.1 | 26 |
| 26 | The corrosion behavior of PCB-ImAg in industry polluted marine atmosphere environment. <i>Materials and Design</i> , 2017, 115, 404-414. | 7.0 | 29 |
| 27 | Corrosion Behavior of Silver-Plated Circuit Boards in a Simulated Marine Environment with Industrial Pollution. <i>Materials</i> , 2017, 10, 762. | 2.9 | 10 |
| 28 | Electrochemical Migration Behavior of Copper-Clad Laminate and Electroless Nickel/Immersion Gold Printed Circuit Boards under Thin Electrolyte Layers. <i>Materials</i> , 2017, 10, 137. | 2.9 | 27 |
| 29 | In situ investigation of atmospheric corrosion behavior of PCB-ENIG under adsorbed thin electrolyte layer. <i>Transactions of Nonferrous Metals Society of China</i> , 2016, 26, 1146-1154. | 4.2 | 17 |
| 30 | Copper corrosion in hot and dry atmosphere environment in Turpan, China. <i>Transactions of Nonferrous Metals Society of China</i> , 2016, 26, 1721-1728. | 4.2 | 21 |
| 31 | Surface analysis of silver-plated circuit boards in a salt-spray environment. <i>Journal of Alloys and Compounds</i> , 2016, 688, 301-312. | 5.5 | 24 |
| 32 | Initial corrosion behavior of a copper-clad plate in typical outdoor atmospheric environments. <i>Electronic Materials Letters</i> , 2016, 12, 163-170. | 2.2 | 9 |
| 33 | Electrochemical migration behavior and mechanism of PCB-ImAg and PCB-HASL under adsorbed thin liquid films. <i>Transactions of Nonferrous Metals Society of China</i> , 2015, 25, 2446-2457. | 4.2 | 13 |
| 34 | Initial Corrosion Behavior and Mechanism of PCB-HASL in Typical Outdoor Environments in China. <i>Journal of Electronic Materials</i> , 2015, 44, 4405-4417. | 2.2 | 10 |
| 35 | Atmospheric corrosion of field-exposed AZ31 magnesium in a tropical marine environment. <i>Corrosion Science</i> , 2013, 76, 243-256. | 6.6 | 137 |
| 36 | Electrochemical migration, whisker formation, and corrosion behavior of printed circuit board under wet H ₂ S environment. <i>Electrochimica Acta</i> , 2013, 114, 363-371. | 5.2 | 61 |

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|----|---|-----|-----------|
| 37 | Localized electrochemical impedance spectroscopy study on the corrosion behavior of Fe-Cr alloy in the solution with Cl^- and SO_4^{2-} . Journal Wuhan University of Technology, Materials Science Edition, 2012, 27, 27-32. | 1.0 | 5 |
| 38 | EFFECT OF MOLD ON CORROSION BEHAVIOR OF PRINTED CIRCUIT BOARD-COPPER AND ENIG FINISHED. Jinshu Xuebao/Acta Metallurgica Sinica, 2012, 48, 687. | 0.3 | 14 |
| 39 | In situ Raman spectroscopy study of corrosion products on the surface of carbon steel in solution containing Cl^- and SO_4^{2-} . Engineering Failure Analysis, 2011, 18, 1981-1989. | 4.0 | 116 |
| 40 | Corrosion products and formation mechanism during initial stage of atmospheric corrosion of carbon steel. Journal of Iron and Steel Research International, 2008, 15, 42-48. | 2.8 | 84 |
| 41 | Correlation between indoor and outdoor corrosion tests for coal train body steel in a coal medium environment. Journal of Iron and Steel Research International, 0, , 1. | 2.8 | 2 |